

(99S0100-1)

COMPOSITION FOR SEALING A SEMICONDUCTOR DEVICE,  
SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING  
THE SAME

as United States Application No. or PCT International Application

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.

**Priority Claimed**

I hereby claim the benefit under 35 U.S.C. 120 of any United States application(s) or 35 U.S.C. 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application or PCT International application in the manner provided by the first paragraph of 35 U.S.C. 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Country of Citizenship: Japan

Masaki Adachi

Country of Citizenship: Japan

Megumi Yamamura

1. **Introduction**